

SURFACE-MOUNT / SMT PRODUCTS

Equipped with Auto Profile Mode. Handles BGAs, CSPs and all SMDs using the preheater.

HOT-AIR REWORK STATIONS
XFC-300/301



AUTO PROFILE
Can be set to the desired profile without a test

VARIOUS PROFILES AVAILABLE
Up to 19 profiles, each with 5 zones

ACCURATE TEMPERATURE CONTROL
With PID control

ON/OFF INTERFACE
Controls external preheater

HAND OPERATION
Heater and vacuum switches on the handpiece

FORCED COOL-DOWN
On all zones with cool key

●Either Auto profile or Repeat Profile function (PAT). ●5 zone profiles available: **PREHEAT 1, PREHEAT 2, PREHEAT 3, REFLOW, and COOL.** ●Up to 19 profiles* can be saved for each of the 5 zones. ●One profile can be registered for HAND Mode. ●Accurate PID temperature control. ●Heater and Vacuum switches located on the handpiece for easy control. ●ON/OFF interface with Preheater (connection cable optional). ●Keypad Lock and Offset functions. ●Instant cool down on all zones by pressing the COOL key.

*separate profiles with specific temperature and time settings can be pre-programmed for each of the 5 Zones



XFC-301



XFC-300

Nozzles sold separately.

Nozzles sold separately.

An economic solution with maximum heat capacity. Handles BGAs, CSPs and all SMDs.

HOT-AIR REWORK STATION
XFC-210



Auto Cool-Down function to protect the heater. Handles QFPs, PLCCs, SOLs.

HOT-AIR REWORK STATION
XFC-110



Nozzles sold separately.



Nozzles sold separately.

ACCURATE TEMPERATURE CONTROL
With P temperature control

ON/OFF INTERFACE
Controls external preheater

TEMPERATURE CONTROL
With ON/OFF control

DIGITAL DISPLAY
Easy temperature control

HAND OPERATION
Heater and vacuum switches on the handpiece

FORCED COOL-DOWN
On all zones with cool key

VACUUM PICK-UP
Highly accurate

FLOW METER
Easy air-flow control

VARIOUS PROFILES AVAILABLE
Up to 19 profiles, each with 5 zones

AUTO COOL-DOWN
Protects the heater

●5 zone profiles available: **PREHEAT 1, PREHEAT 2, PREHEAT 3, REFLOW, and COOL.** ●Up to 19 profiles* can be saved for each of the 5 zones. One profile can be registered for HAND Mode. ●Accurate P temperature control. ●Heater and Vacuum switches located on the handpiece for easy control. ●ON/OFF interface with Preheater (connection cable optional). ●Keypad Lock and Offset functions. ●Instant cool down on all zones by pressing the COOL key.

●Temperature management using ON-OFF control. ●Digital temperature display for easy temperature management. ●Vacuum pickup function, Flow meter for easy airflow management. ●Auto Cool Down function to protect heater.

*individual profiles with specific temperature and time settings can be pre-programmed for each of the 5 Zones

XFC series FEATURES TABLE

FUNCTION	XFC-301	XFC-300	XFC-210	XFC-110
Auto-lift*	✓	—	—	—
5-zone Profiles	✓	✓	✓	—
Auto Profile Mode	✓	✓	—	—
Normal Profile Mode	✓	✓	✓	—
Hand Mode	✓	✓	✓	✓
Saving of Profile Mode and Hand Mode	✓	✓	✓	—
PID Control	✓	✓	P control	—
ON/OFF and Vacuum Control on Handpiece	✓	✓	✓	—
Interface to Control Preheater	✓	✓	✓	—
Keypad Lock, Offset	✓	✓	✓	—
Forced Cool-down	✓	✓	✓	✓
Vacuum Pick-up	✓	✓	✓	✓
Digital Display	✓	✓	✓	✓
Flow Meter	✓	✓	✓	✓
Auto Cool-down	—	—	✓	✓
Ergonomic Handpiece	✓	✓	✓	✓

*Handpiece with removed SMD can be lifted automatically after the reflow process is finished.

SPECIFICATIONS

Model	XFC-301	XFC-300	XFC-210	XFC-110
Voltage	220–240 V AC 50/ 60 Hz		220 V, 230 V, 240 V AC 50/ 60 Hz	
Power Consumption	400–460 W		470 W	
Power Cord Length	1.5 m (3 core cord) Inlet type			
Temperature Setting Range	50–550°C			150–550°C
Insulation Resistance	Over 10 MΩ (500 V DC)			

Control Unit

Model	XFC-301	XFC-300	XFC-210	XFC-110
Output Voltage	220–240 V AC		220 V, 230 V, 240 V AC	
Air-flow Meter	Equipped			
Air-flow Volume	5–25L /min		5–23L /min	5–25L /min
Auto-lift Function	Included		-	
Modes	3 (Profile-Normal, Profile-Auto, Hand)		3 (Profile-Flat, Profile-Slope, Hand)	1 (Hand)
Temperature Profiles	5 Zones (Temperature and Time)			
Profile Memory	(Auto, Normal)×19, HAND×1		(Flat,Slope)×19, HAND×1	
Dimensions	200 (W) ×230 (H) ×265 (D) mm		182 (W) ×179 (H)× 263 (D) mm	
Weight	7.6 kg (w/o cord)		8.4 kg (w/o cord)	7.8 kg (w/o cord)
Accessory	Connection Cable with Preheater, Handpiece Holder, XVCW-SET			Handpiece Holder, XVCW-SET

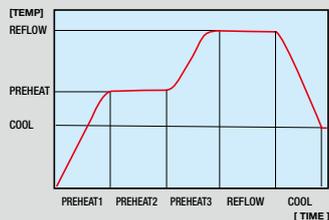
Handpiece Unit

Model	XFC-301	XFC-300	XFC-210	XFC-110
Voltage	220-240 V AC		220 V, 230 V, 240 V AC	
Power Consumption	370-430 W		400 W	
Heater	Nichrome Heater			
Hose Length between Handpiece and Control Unit	1 m			
Vacuum Pickup	Integrated into Handpiece			
Length	220 mm (w/o cord)			
Weight	180 g (w/o nozzle, cord)			

MODES

NORMAL	Create your own profiles for the 5 zones.
AUTO	Can be set to the desired profile without a test. (PAT.) XFC-301/300 only
HAND	Configure temperature settings for manual rework.

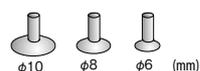
XFC-301/300 AUTO PROFILE EXAMPLE



REPLACEMENT PARTS / OPTIONS

Heater XFC-100H	Vacuum Cup ø6 mm XVCW-6
XFC Heater Pipe XFC-100HP	Vacuum Cup ø8 mm XVCW-8
Vacuum Cup Set XVCW-SET	Vacuum Cup ø10 mm XVCW-10

Vacuum Cup



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XFC-301

XFC-300



XFC-210

XFC-110

PREHEATERS p.65



XPR-610



XPR-600



XPR-1000

HANDPIECE HOLDERS p.64



XK-1



XK-2

BOARD HOLDERS p.65



XU-1

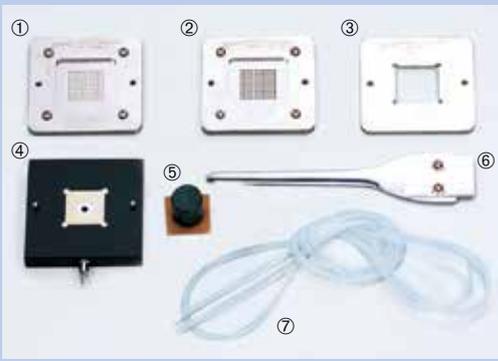
XU-1S



Reball Kit allows replacement of solder balls on a BGA.



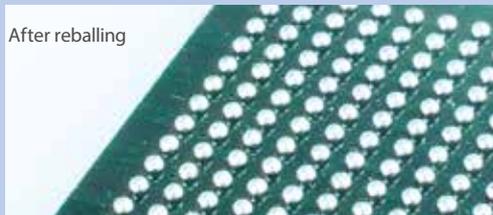
REBALL KIT XRB series



①	Metal Mask (Mask Plate included)
②	Ball Guide (Mask Plate included)
③	Guide Plate
④	Base
⑤	Tamper
⑥	Spatula
⑦	Hose (to connect the Base with the vacuum source)

XRB Reball Kits are customized for specific BGAs. Please send us the technical drawings of your BGA.

Also required to reball components: Hot-air rework station (XFC-110/210/300/301), soldering iron, desoldering wick, cream solder, and solder balls. (Sold separately.)



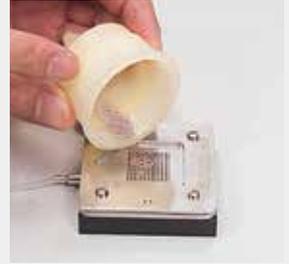
1. Remove the existing solder balls on the BGA chip with a soldering iron and a desoldering wick.



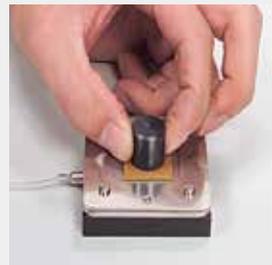
2. Set the Guide Plate on the base, and hold the BGA with the vacuum source.



3. Set the Metal Mask. Use the spatula to apply the cream solder to all the holes.



4. Mount the Ball Guide. Pour the solder balls into the holes.



5. Press the solder balls into the cream solder with the tamper.



6. Take out the BGA from the base, and apply heat.

